

The SiliconBlue logo features the word "SiliconBlue" in a white serif font. The "i" in "Silicon" is lowercase, while "Blue" is uppercase. A dark blue circle is positioned behind the "B" in "Blue". The logo is set against a background of light blue rays emanating from a bright point at the top left, creating a sunburst effect.

SiliconBlue

Ultra Low Power FPGA Fuels Faster Feature Evolution in Mobile Applications

John Birkner

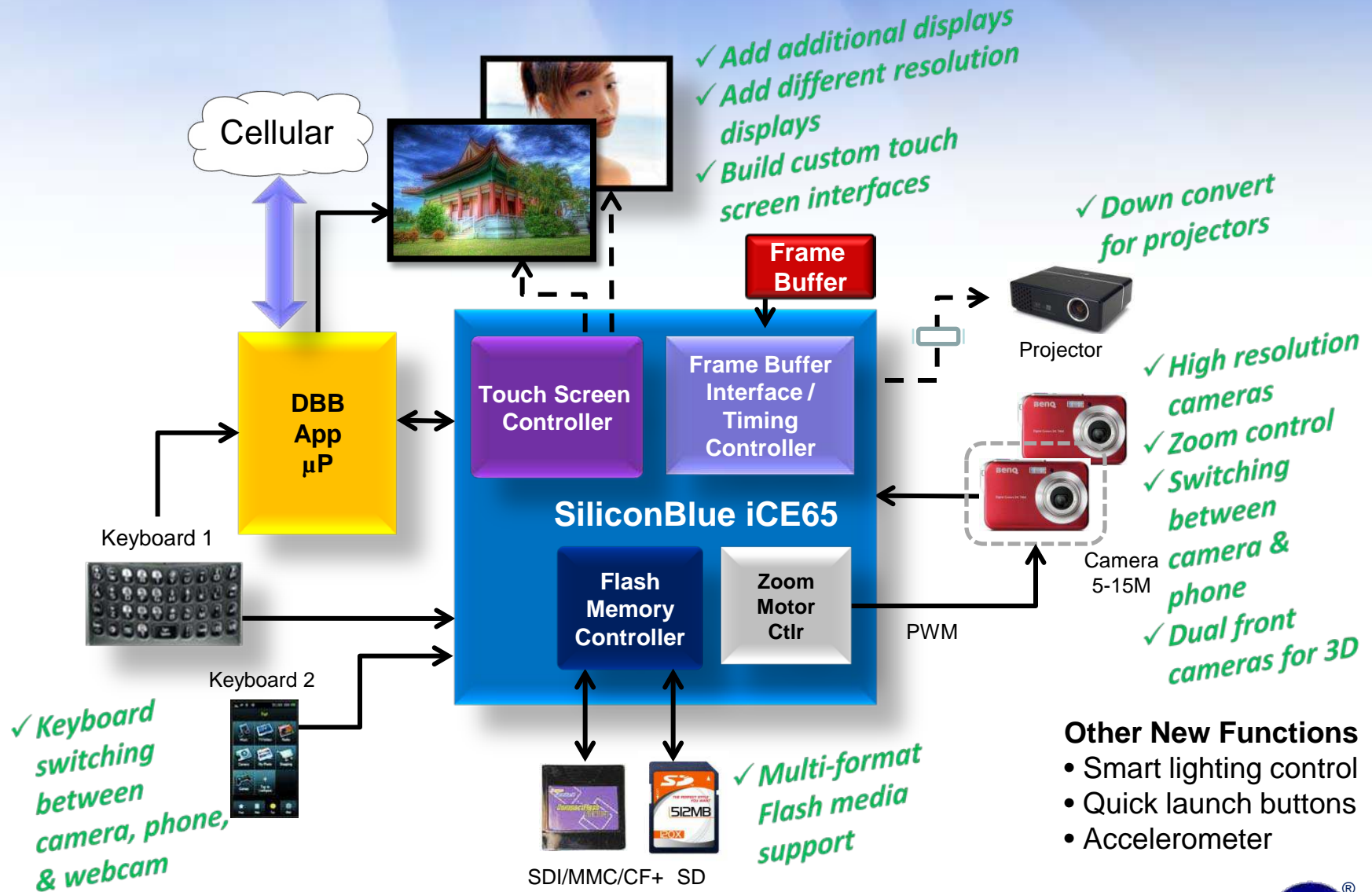
VP, Strategic Marketing

SiliconBlue Technologies

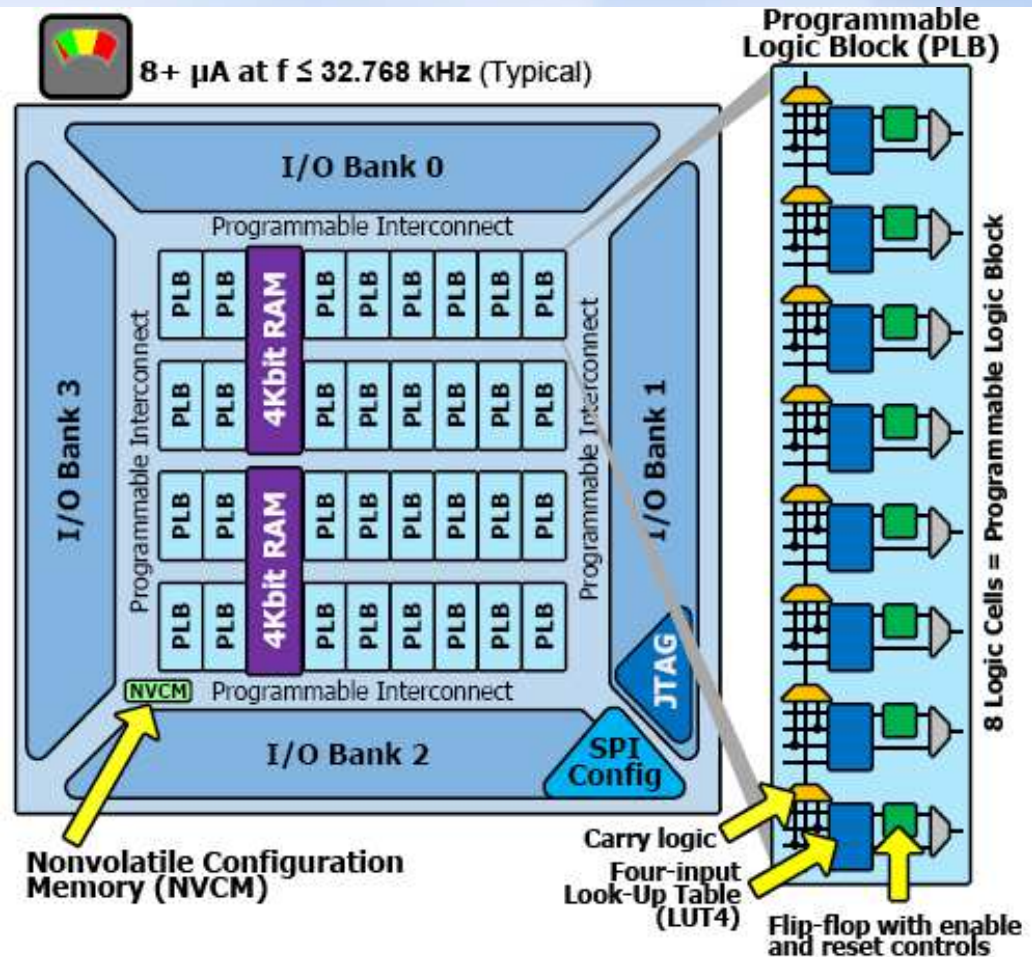
Ultra-low power, Single-chip SRAM FPGA Targets Handheld Consumer Applications



What Solutions does FPGA provide?

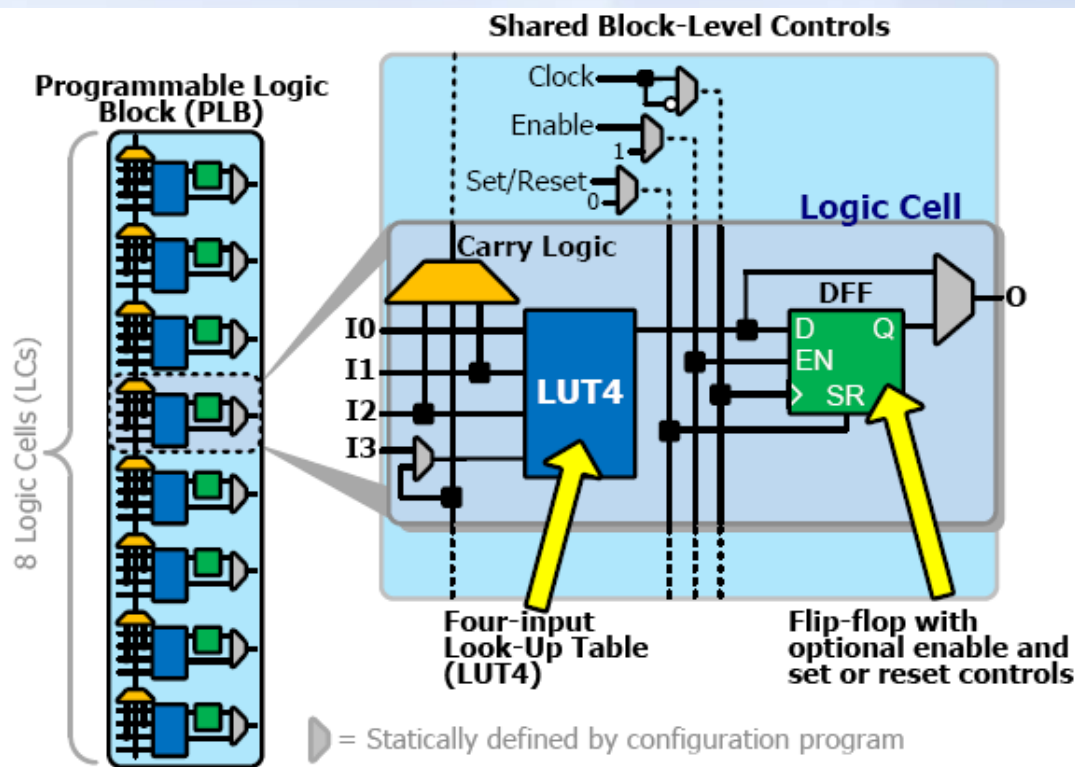


iCE65 FPGA Architecture



- Ultra low power
- Array of Programmable Logic Blocks (PLBs)
- Surrounded by four I/O Banks
- 4Kbit RAM Blocks
- Programmable interconnect
- Non-Volatile Configuration Memory (NVCM)
- SPI interface

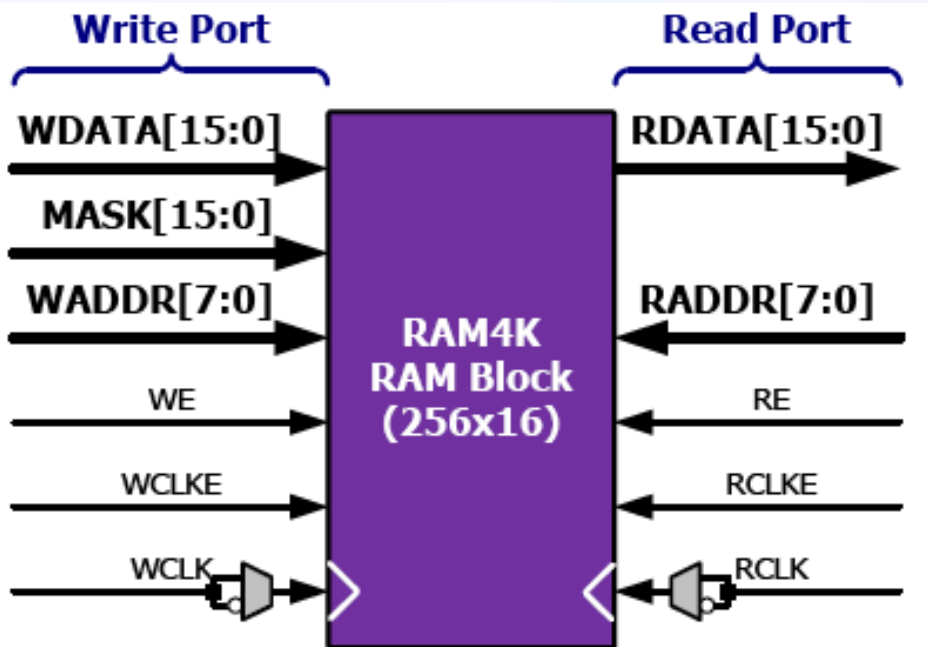
Programmable Logic Block (PLB)



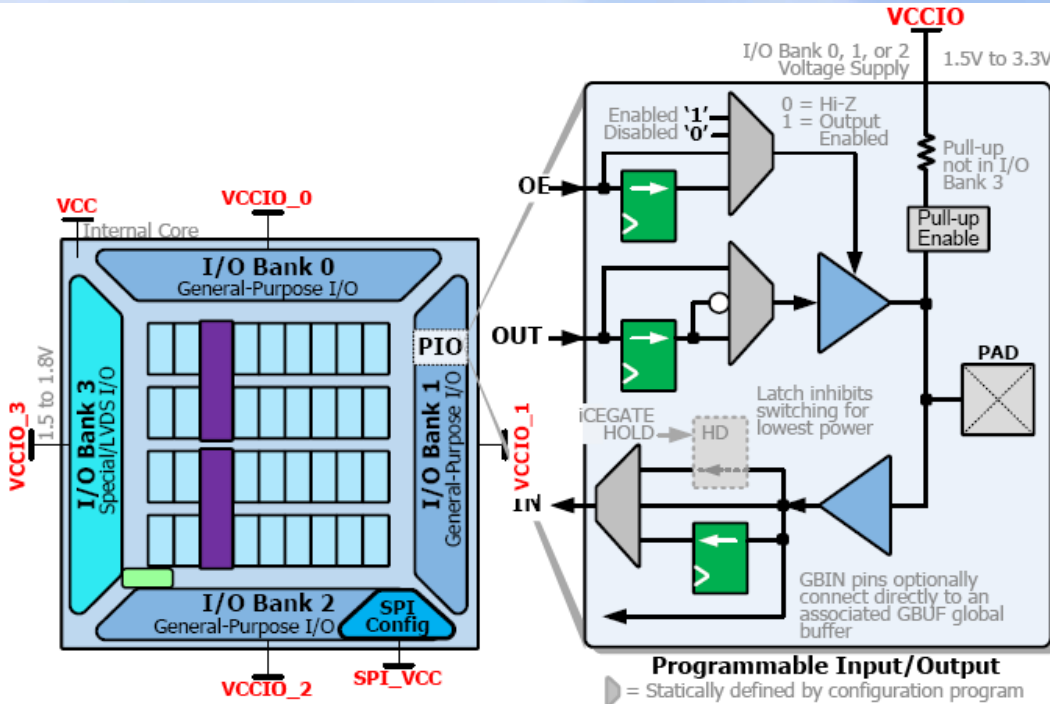
- Eight 4-input Look-up Tables (LUT4)
- Eight 'D' flip-flops with shared clock, clock enable, set/reset control
- Fast carry logic
- Familiar, well supported by logic synthesis tools

RAM 4K Memory Block

- Implements variety of functions:
 - Random-access memory (RAM)
 - Single-port RAM with a common address, enable, and clock control lines
 - Two-port RAM with separate read and write control lines, address inputs, and enable
 - Register file and scratchpad RAM
 - First-In, First-Out (FIFO) memory for data buffering applications
 - Circuit buffer
 - 256-deep by 16-wide ROM with registered outputs, contents loaded during configuration
 - Sixteen different 8-input look-up tables
 - Function or waveform tables such as sine, cosine, etc.
 - Correlators or pattern matching operations
 - Counters, sequencers



Programmable Input/Output (PIO)



I/O Standards:

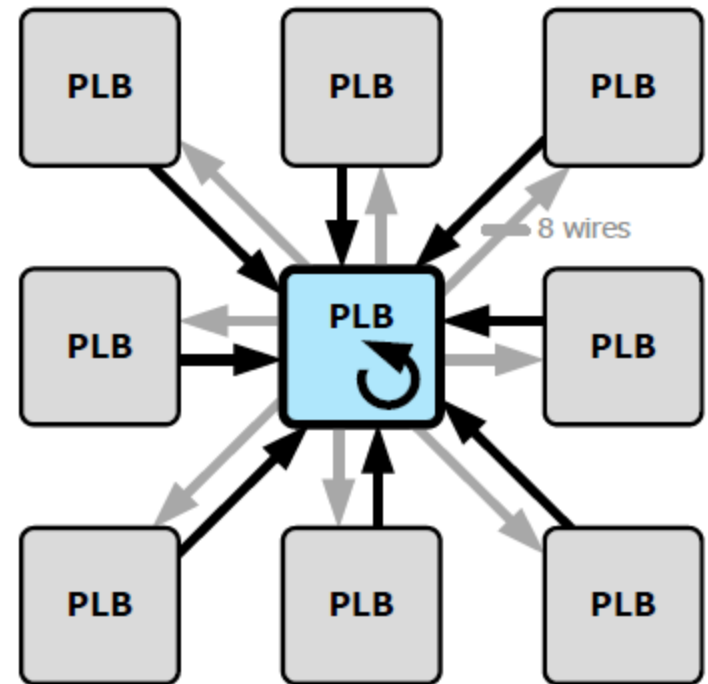
LVC MOS33	LVC MOS25, LVDS	LVC MOS18
LVC MOS18	SubLVDS	LVC MOS15
SSTL25	SSTL18	MDDR

Bank	Device Edge	Supply Input	3.3V	2.5V	1.8V	1.5V
0	Top	VCCIO_0	Yes	Yes	Yes	Outputs only
1	Right	VCCIO_1	Yes	Yes	Yes	Outputs only
2	Bottom	VCCIO_2	Yes	Yes	Yes	Outputs only
3	Left	VCCIO_3	No	Yes	Yes	Yes
SPI	Bottom Right	SPI_VCC	Yes	Yes	Yes	No

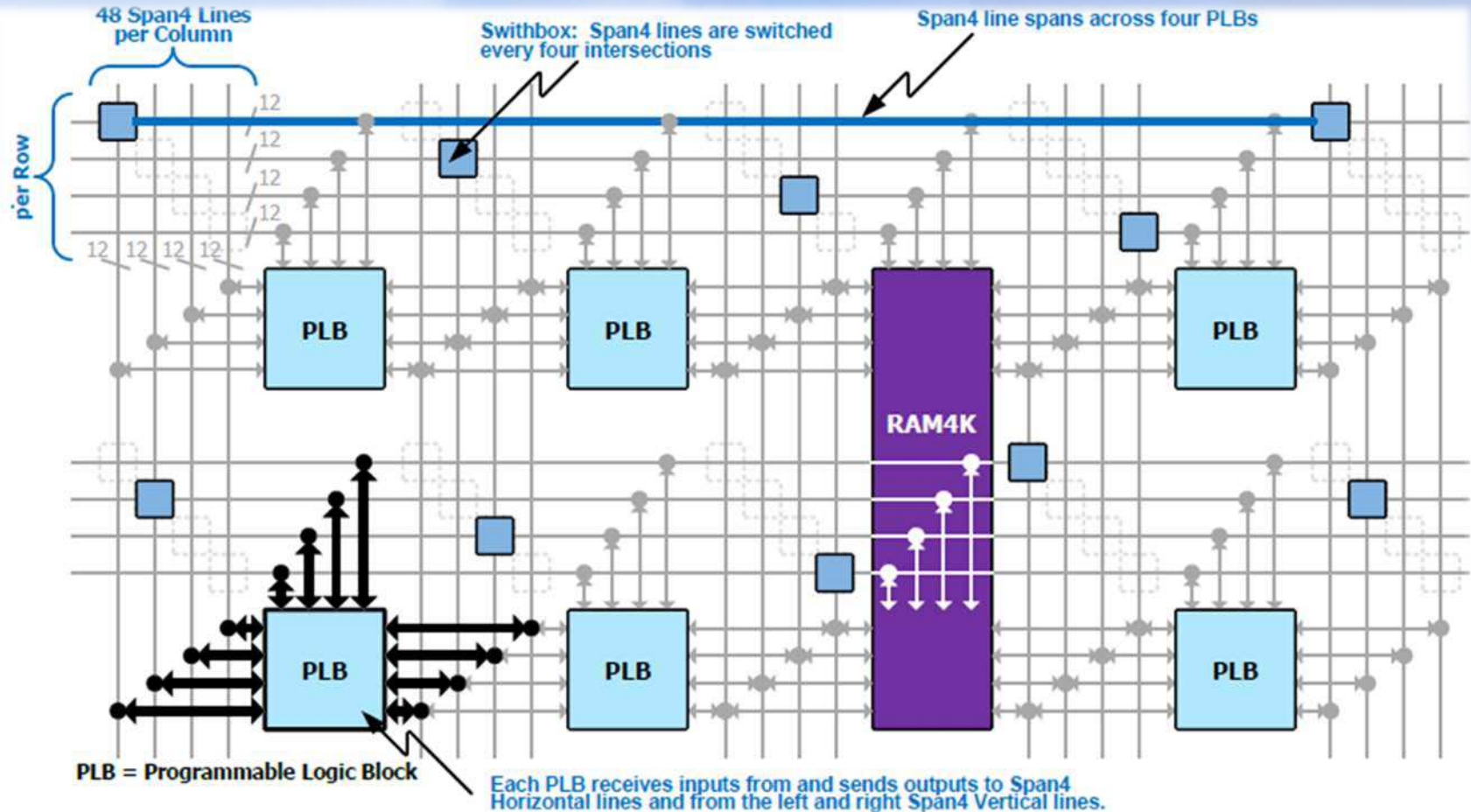
- Connects external components to the PLBs and RAM4K blocks via programmable interconnect
- Individual pins grouped into 1-of-4 I/O banks
 - Multi-functions
- I/O Bank #3 has add'l functionality
 - LVDS differential I/O
 - Mobile DDR memory interface

Programmable Interconnect

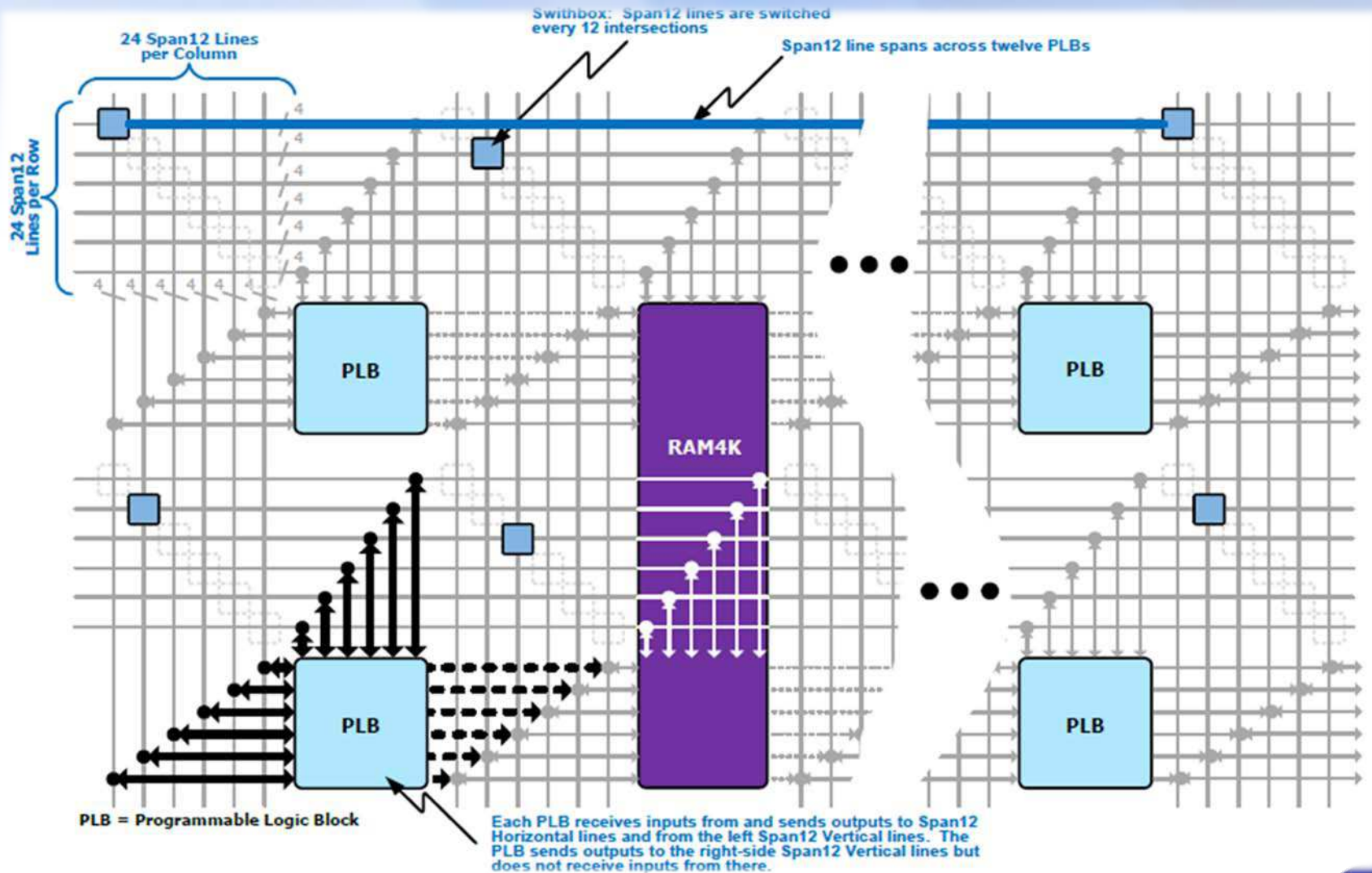
- Hierarchy of resources:
 - Nearest Neighbor Connections between a PLB and its surrounding neighbors
 - Span4 Connections & switchboxes
 - Span12 Connections & switchboxes



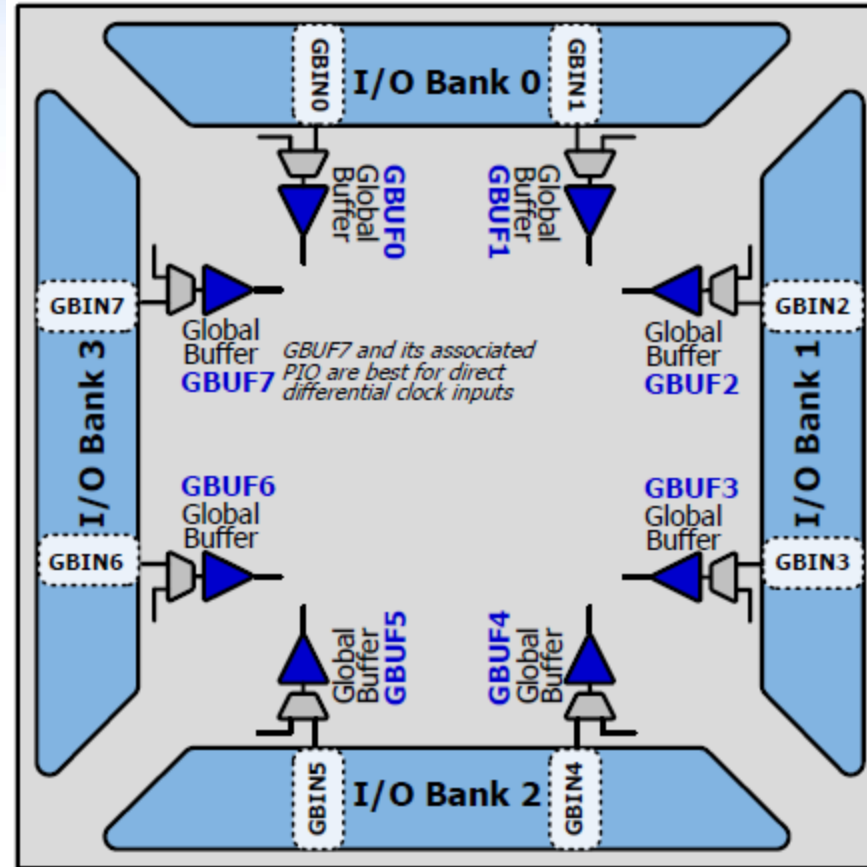
Span4 Connection Resources



Span12 Connection Resources

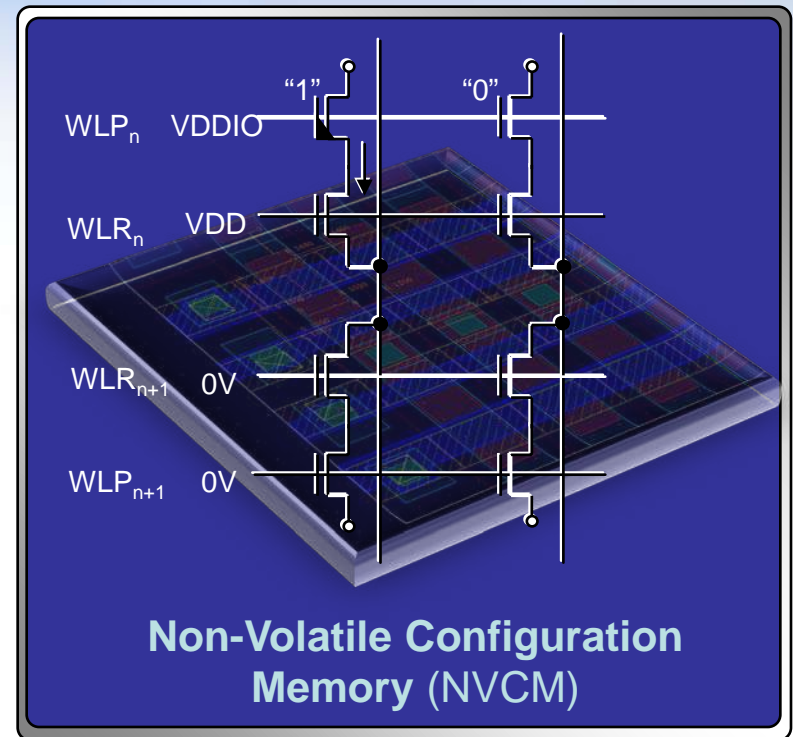


Global Routing Resources



Unique Self-Configuration Option (NVCM)

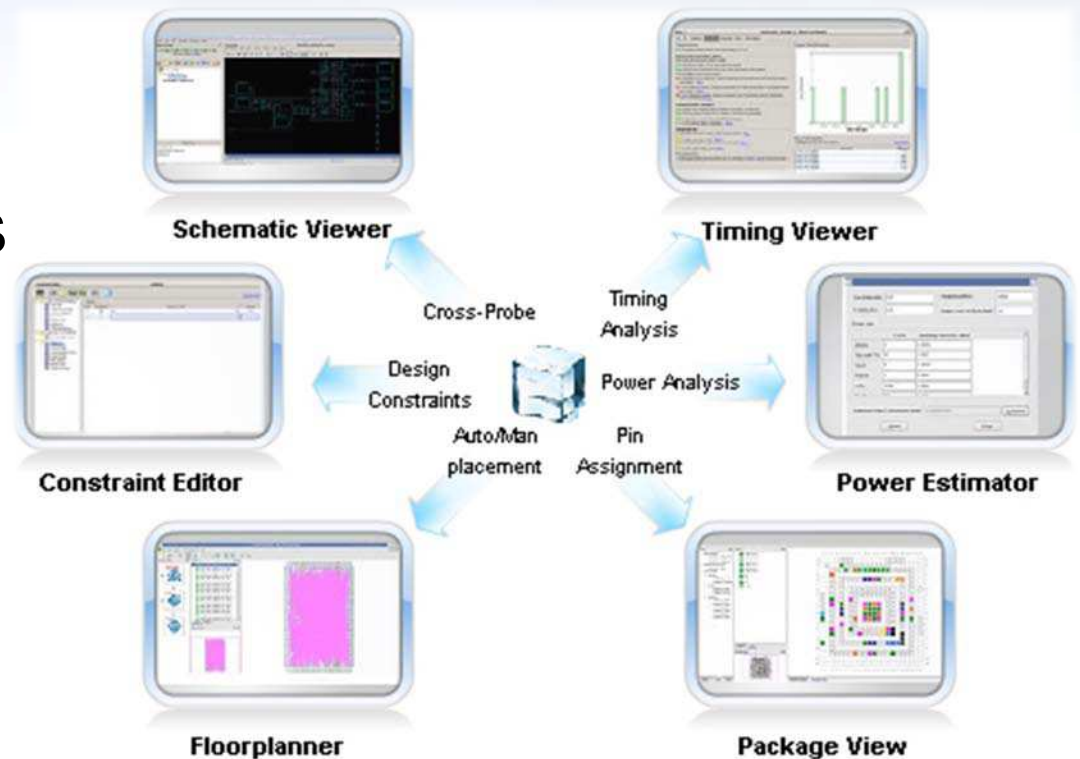
- Industry's only single chip, SRAM FPGA
 - Reprogrammable, reconfigurable as any SRAM FPGA thru SPI port in milliseconds
 - NVCM configures on power up
 - Secure
- Uses TSMC 65LP¹ standard CMOS process
 - Smallest die, lowest cost
 - Rapidly ramp volume



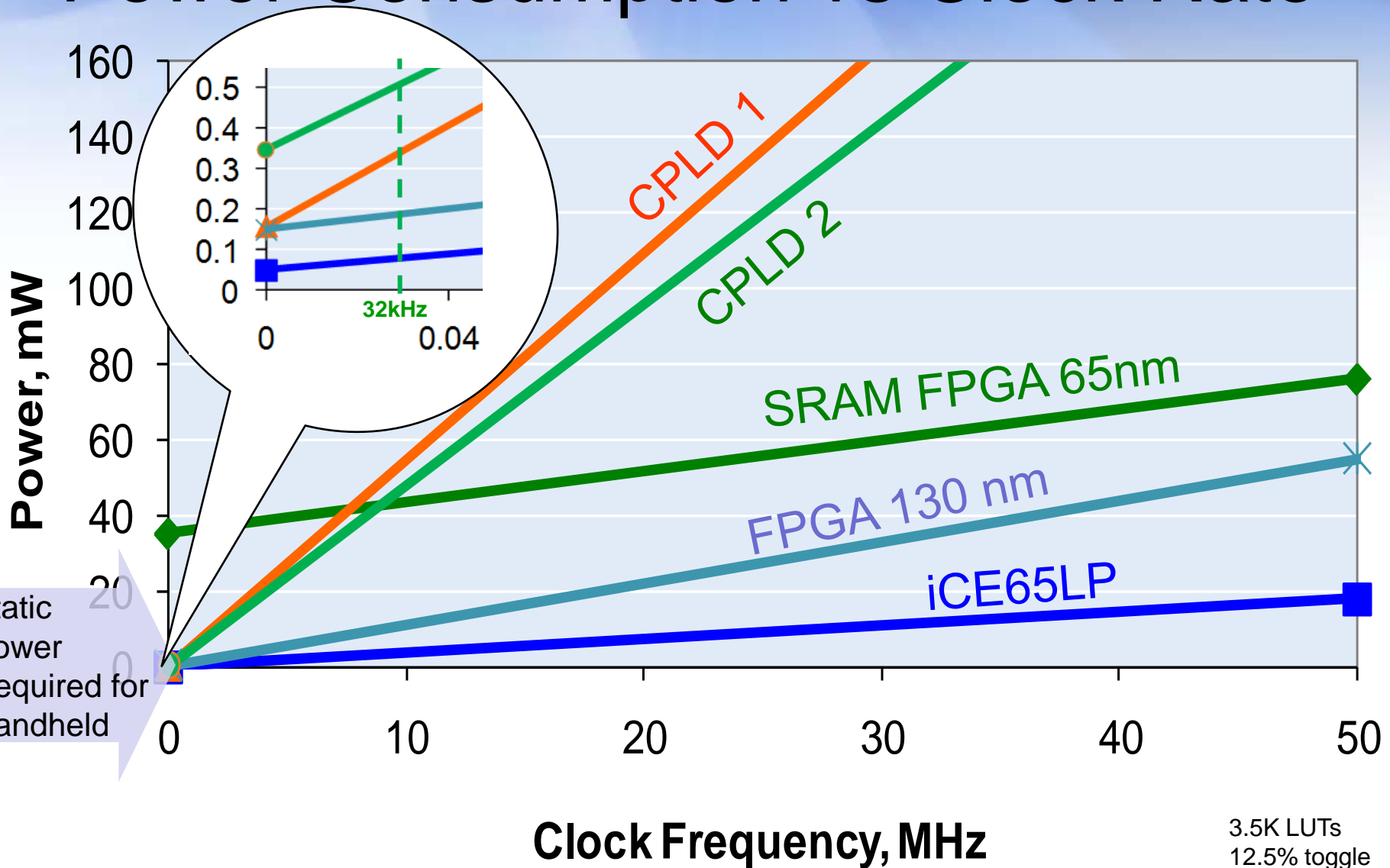
Note 1. Two generation competitive lead versus Flash FPGAs

iCEcube Design Tool Suite

- Verilog & VHDL
- Timing driven physical synthesis
Magma tools
- Windows or Linux
- Power Analysis & Management tools



Power Consumption vs Clock Rate

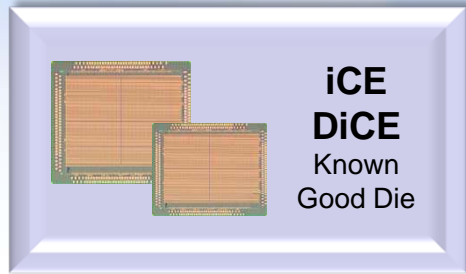


3.5K LUTs
12.5% toggle

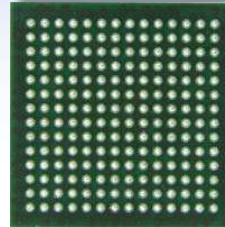
iCE65 mobileFPGA™ Family

Features	iCE65L02	iCE65L04	iCE65L08	iCE65L16
FPGA System Gates	~100K	~200K	~400K	~800K
Logic Cells	1,792	3,520	7,680	16,896
Programmable I/O _(max I/O / LVDS channels)	128/18	176/20	222/25	384/54
Embedded RAM Bits	64K	80K	128K	384K
Sleep current (0 KHz, V _{cc} =0.8V)	3 μA	5 μA	11 μA	50 μA
Dynamic current (32 KHz) ¹	8 μA	15 μA	30 μA	75 μA
Dynamic current (32 MHz) ¹	3 mA	6 mA	12 mA	24 mA
Availability	NOW	NOW	NOW	2010

iCE65 Small Form Factor Solutions

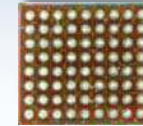


CB196
L04, L08
(150/18)



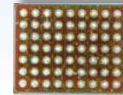
.5 mm pitch
8x8 mm

CC72
L08 (55/8)



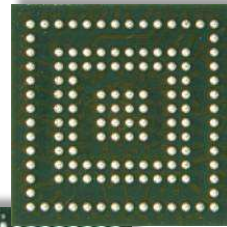
.5 mm pitch
4x5 mm

CS63
L04 (48/4)



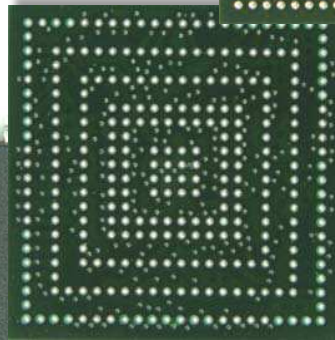
.4 mm pitch
3x4 mm

CB132
L02, L04
(95/11)



.5 mm pitch
8x8 mm

CB284
L04, L08, L16
(222/25)



.5 mm pitch
12x12 mm

VQ100
L04
(72/9)¹



.5 mm pitch
14x14 mm



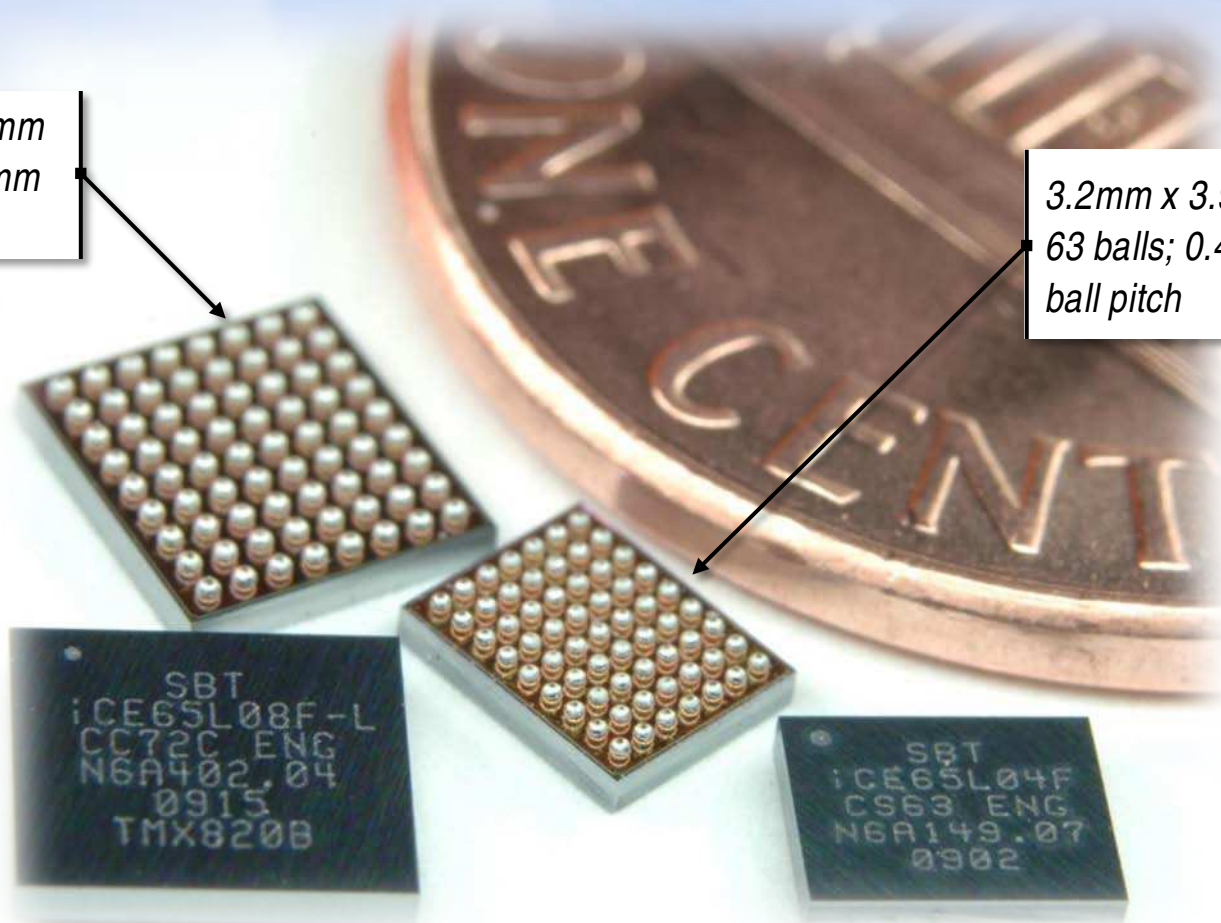
¹(Max I/O / Diff Pairs)

Wafer Level Chip Scale Packages

Optimized for Small Handheld Products

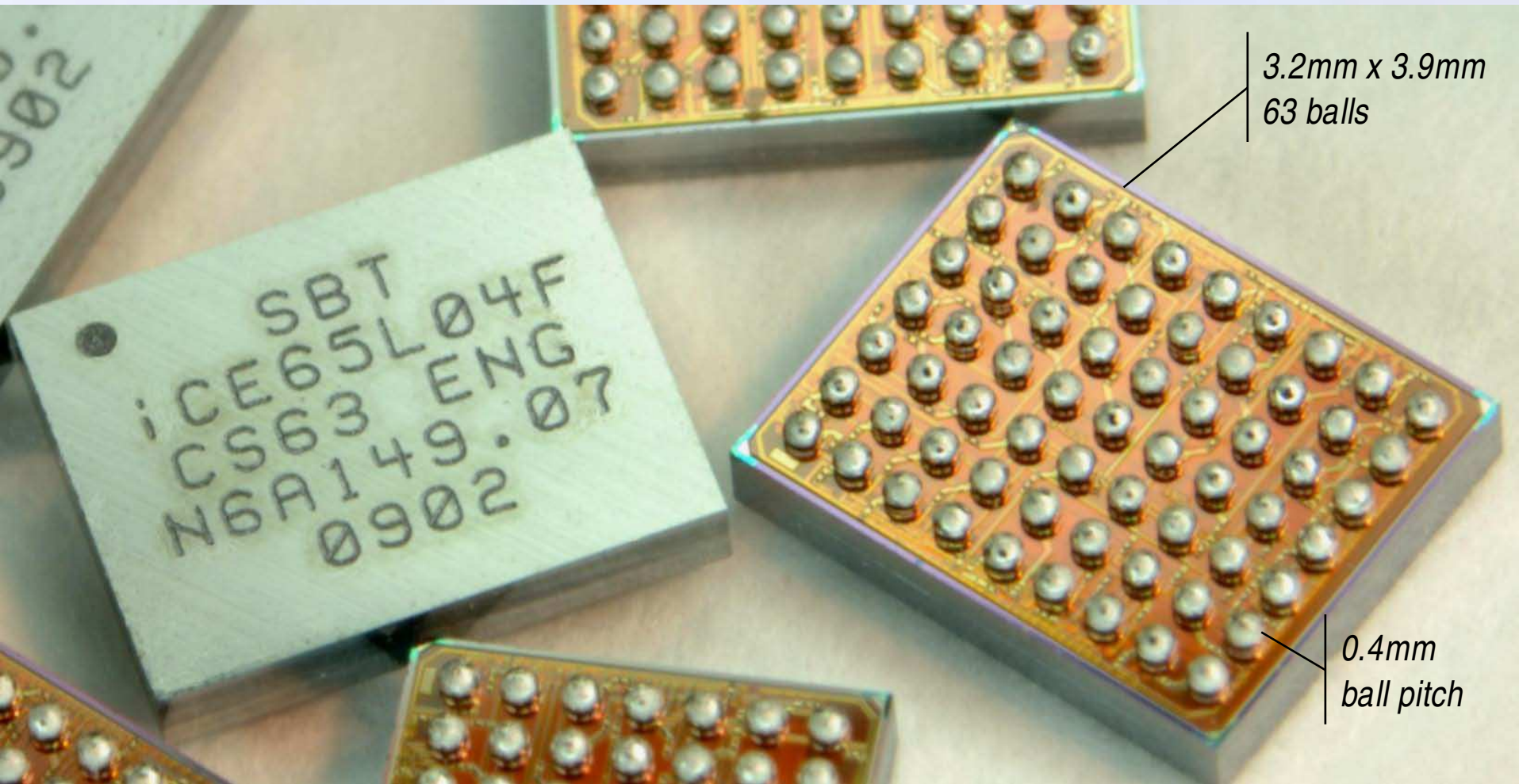
4.4mm x 4.8mm
72 balls; 0.5mm
ball pitch

3.2mm x 3.9mm
63 balls; 0.4mm
ball pitch



Small Form Factor WLCSP: .4mm pitch

- Key Features:**
- ~200K System Gates
 - 48 I/Os; 4 diff pairs
 - $I_{cc0\text{ sleep}} = 5\mu\text{A}$
 - $I_{cc32K} = 15\mu\text{A @ } 32\text{KHz}$



iCE65L04 & iCE65L08 FPGAs

Known Good Die

ICE DiCE™:
iCE65L04 Ultra Low-Power
FPGA Known Good Die



ICE DiCE™:
iCE65L08 Ultra Low-Power
FPGA Known Good Die

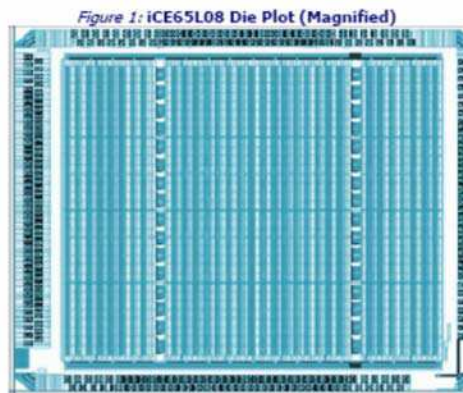


March 23, 2009 (1.0.3)

Advance Information (SUBJECT TO CHANGE)

Features

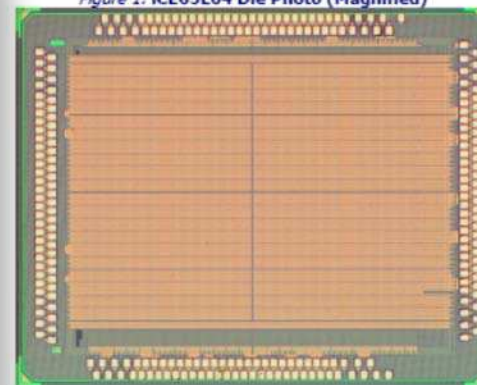
- **First ultra low-power programmable logic family specifically designed for hand-held applications and long battery life**
 - ◆ Less than 30 μ A typical standby current (~U); no special power down modes required
 - ◆ Lowest active power consumption of any comparable programmable logic family
 - ◆ Lowest heat dissipation on power-sensitive applications
- **Known Good Die (KGD)**
 - ◆ Ideal for System-in-Package (SiP), stacked-die, or multi-chip module applications
 - ◆ Ideal for Chip on Board (COB) mounting in low-cost consumer products
 - ◆ Various temperature range, thickness, and delivery method options
- **Reprogrammable from a variety of sources**
 - ◆ Self-loading from secure, internal Nonvolatile Configuration Memory (NVCN)
 - Superior design and intellectual property (IP) protection; no exposed configuration data
 - Single-chip programmable solution
 - Low-cost, high-volume configuration source
 - ◆ Self-loading from external, commodity SPI serial Flash PROM
 - ◆ Downloaded by processor using SPI-like serial interface
- **Built on proven, high-volume 65 nm, low-power CMOS technology delivering lowest possible power and cost**



- **Up to 200+ MHz internal performance**
- **Flexible programmable logic and programmable interconnect fabric**
 - ◆ Over 7,500 four-input look-up tables (LUT4) and flip-flops
 - ◆ Low-power logic and interconnect
- **On-chip, 4Kbit RAM blocks; 32 per device**
- **Flexible I/O blocks to simplify system interfaces**
 - ◆ 222 programmable I/O pads
 - ◆ Four independently-powered I/O banks support 3.3V, 2.5V, or 1.8V voltage standards
 - ◆ Differential LVDS I/O pairs

Preliminary (SUBJECT TO CHANGE)

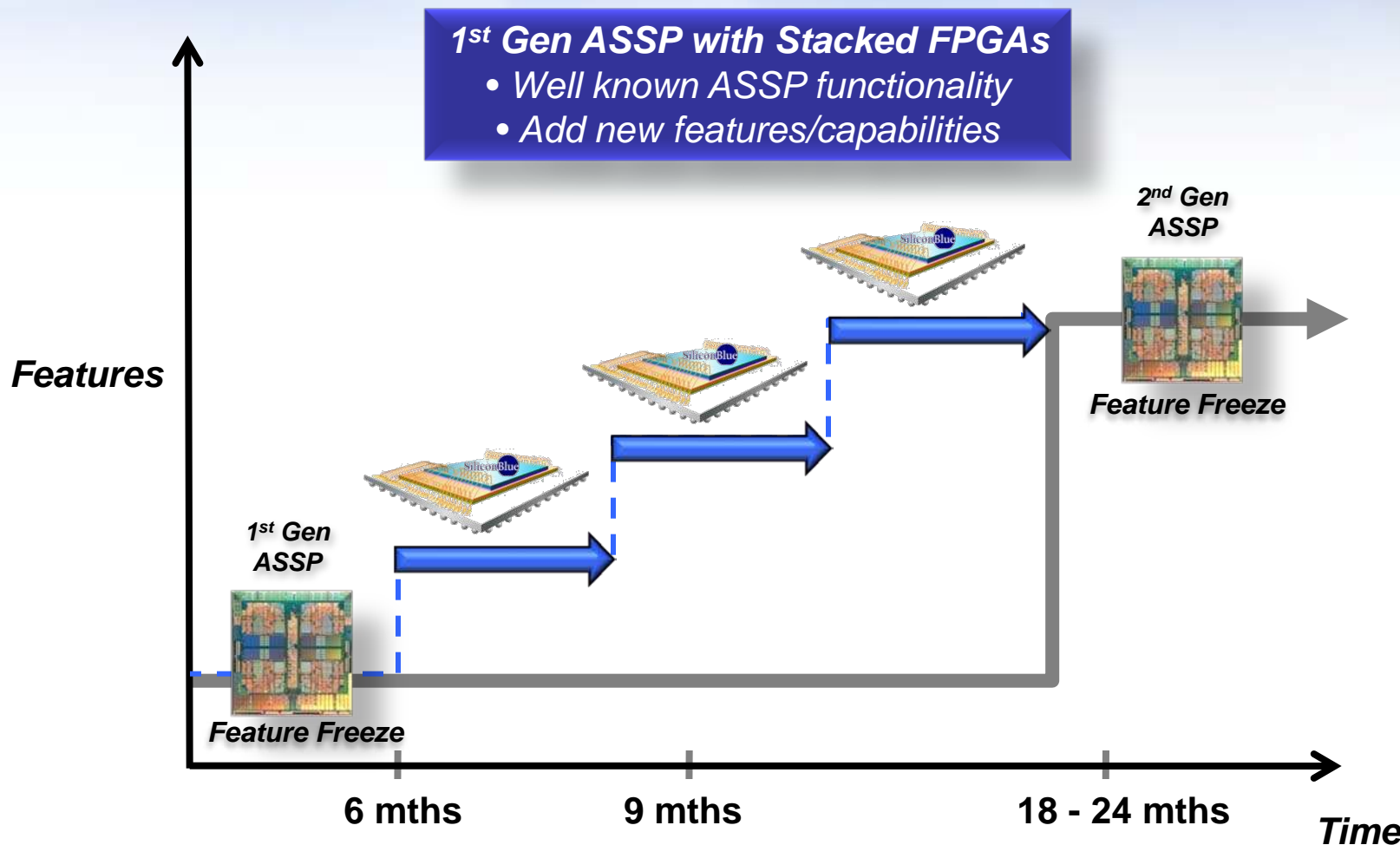
Figure 1: iCE65L04 Die Photo (Magnified)



- **Up to 200+ MHz internal performance**
- **Flexible programmable logic and programmable interconnect fabric**
 - ◆ Over 3,500K four-input look-up tables (LUT4) and flip-flops
 - ◆ Low-power logic and interconnect
- **On-chip, 4Kbit RAM blocks; 20 per device**
- **Flexible I/O blocks to simplify system interfaces**
 - ◆ 176 programmable I/O pads
 - ◆ Four independently-powered I/O banks support 3.3V, 2.5V, or 1.8V voltage standards
 - ◆ Differential LVDS I/O pairs



New Products, New Features, More Revenue



Example SiliconBlue IP: Smartphone

Turn-Key Solutions	Resources			
	FFs	LUTs	IOs	RAMs
48 Channel PWM Controller with I2C Interface	230	416	66	3
Backlighting Controller with Ambient Light Awareness	138	223	53	0
I2C Port Expansion Demo	74	251	66	0
Decoded Keyboard Output	891	891	76	0
Display on Character LCD				
Digital Picture Frame with Touch Screen	365	1254	47	5
Interactive Control of Tri-Color LEDs with PWM	90	143	63	0
48 Channel PWM Controller with SPI Interface	199	369	68	3
Voltage Level Translation Demo	0	0	7	0
SPI Port Expansion Demo	33	79	68	0
Processors				
8051 Processor	In Development*			
Embedded Processor Configuration	In Development*			
Interfaces				
I2C Master	98	196	15	0
I2C Slave	34	84	19	0
IrDA Fast	225	542	41	2
IrDA Standard	38	81	6	0
SPI Master	218	402	31	2
SPI Master for OMAP	217	401	30	2
SPI Slave	33	7	36	0
UART	140	345	30	2
Voltage Level Translation	0	0	16	0
LVDS Serializer	In Development*			
LVDS De-Serializer	In Development*			

Peripherals	Resources			
	FFs	LUTs	IOs	RAMs
I2C to GPIO Port Expander	34	84	19	0
Keyboard Matrix Decoder	41	126	23	0
Multi-Function Port Expander	667	1565	54	8
PWM Generation	25	47	6	0
SPI to GPIO Port Expander	33	71	36	0
SPI to UART Port Expander	143	244	174	0
Touch Screen Controller	80	146	17	0
UART to UART Port Expander	10	18	28	0
Audio Data Buffer	In Development*			
Capacitive Button/Slider Controller	In Development*			
MDDI Controller	In Development*			
MP3 Decoder	In Development*			
Storage				
MemoryStick Pro Interface	101	230	33	0
SD Interface and Controller	508	1180	45	8
SDIO Interface and Controller	507	1167	45	8
SD to SD Card Copy	In Development*			
SD Full Featured Controller	In Development*			
Displays				
Graphics LCD Controller (320x240, 18-bit color)	133	415	63	0
Capacitive Touchscreen Controller	In Development*			
CMOS Imager Interface	In Development*			
Dual Display Controller	In Development*			
Preview/Review Display Controller	In Development*			
SVGA Frame Buffer	In Development*			
Memories				
Cellular RAM Controller	305	753	96	2
NAND Flash Interface	4	20	16	0
MDDR Controller	In Development*			
SL to ML NAND Flash Converter	In Development*			
MLC NAND Flash Controller	In Development*			

Summary: Best FPGA for Consumer Handheld

SiliconBlue

mobileFPGA™

- “Green” solution
- Ultra-low power
- High density
- Smallest footprint
- Low price
- Single chip
- Maximum design flexibility

Key Functions

- *Interfaces*
- *Controllers*
- *Peripherals*
- *Glue logic*
- *More.....*

High Value Benefits

- *Quickly customize off-the-shelf chips*
- *Create end product differentiation*
- *Simplify functional “convergence”*
- *Improve time-to-market*

